

providing a first integrated circuit having a surface;

disposing first and second terminal pads on the surface of the first integrated circuit;

forming an electrically conductive connection between the first and second terminal pads of the first integrated circuit;

D²inx
providing a second integrated circuit having a surface;

C¹nt
disposing first and second terminal pads on the surface of the second integrated circuit;

providing a protective structure acting as a switch that becomes conductive when there is an overvoltage to dissipate an electrostatic discharge to a line for a supply voltage;

electrically coupling at least the first terminal pad of the second integrated circuit to the protective structure;

disposing the surfaces of the first and second integrated circuits longitudinally adjacent one another so that the first and second terminal pads of the second integrated circuit are not covered by the first integrated circuit;

C¹ until
electrically joining at least one of the first and second terminal pads of the first integrated circuit to one of the first and second terminal pads of the second integrated circuit;

D² until
severing the electrically conductive connection using an energy pulse.
